L Number			DB	Time stamp
/	2328	wafer and (adhesi\$4 and barrier) adj	USPAT;	2004/08/26 15:00
3		(layer or film)	US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			1	
8	14	(wafer and (adhesi\$4 and barrier) adj	IBM_TDB USPAT;	2004/00/26 15 00
		(layer or film)) and photo near	US-PGPUB;	2004/08/26 15:00
		(lithograph\$6 and resist) and etch\$4	EPO; JPO;	
	ļ	J special representations of the second representation of the second repre	DERWENT;	
	1		IBM TDB	
9	11	((wafer and (adhesi\$4 and barrier) adj	USPAT;	2004/08/26 14:59
		(layer or film)) and photo near	US-PGPUB;	,,
		(lithograph\$6 and resist) and etch\$4) and	EPO; JPO;	
		solder	DERWENT;	
1.0			IBM_TDB	
10	1	("20020064935").PN.	USPAT;	2004/08/26 14:58
11	_	(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB	
11	1	("20030099767").PN.	USPAT;	2004/08/26 14:59
12	22200		US-PGPUB	
12	32288	solder near (bump or ball or sphere or	USPAT;	2004/08/26 14:59
		block or preform)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
13	1228	(solder near (bump or ball or sphere or	<pre>IBM_TDB USPAT;</pre>	2004/00/26 35 00
		block or preform)) and (solder or bump or	US-PGPUB;	2004/08/26 15:00
		ball or sphere or block or preform) near	EPO; JPO;	1
	}	(column or stack\$4 or tower)	DERWENT;	
		· · · · · · · · · · · · · · · · · · ·	IBM TDB	]
14	288	((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:00
		block or preform)) and (solder or bump or	US-PGPUB;	====, ==, ==, ===
		ball or sphere or block or preform) near	EPO; JPO;	İ
	i	(column or stack\$4 or tower)) and (solder	DERWENT;	
		or bump or ball or sphere or block or	IBM_TDB	Í
1.5		preform) near (stack\$4)		
15	14	(((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:01
		block or preform)) and (solder or bump or	US-PGPUB;	
		ball or sphere or block or preform) near (column or stack\$4 or tower)) and (solder	EPO; JPO;	
		or bump or ball or sphere or block or	DERWENT;	
		preform) near (stack\$4)) and wafer and	IBM_TDB	
		(adhesi\$4 and barrier) adj (layer or film)		
16	0	((((solder near (bump or ball or sphere	USPAT;	2004/08/26 15:01
		or block or preform)) and (solder or bump	US-PGPUB;	
		or ball or sphere or block or preform)	EPO; JPO;	
		near (column or stack\$4 or tower)) and	DERWENT;	
		(solder or bump or ball or sphere or block	IBM_TDB	
		or preform) near (stack\$4)) and wafer and	-	
		(adhesi\$4 and barrier) adj (layer or film)		
17	3.0	) and photo near (lithograph\$6 and resist)		
17	30	((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:01
		block or preform)) and (solder or bump or	US-PGPUB;	
	İ	ball or sphere or block or preform) near (column or stack\$4 or tower)) and wafer	EPO; JPO;	
		and (adhesi\$4 and barrier) adj (layer or	DERWENT;	
		film)	IBM_TDB	
18	0	(((solder near (bump or ball or sphere or	IICDAT -	2004/00/20 35 03
		block or preform)) and (solder or bump or	USPAT; US-PGPUB;	2004/08/26 15:01
		ball or sphere or block or preform) near	EPO; JPO;	
		(column or stack\$4 or tower)) and wafer	DERWENT;	
		and (adhesi\$4 and barrier) adj (layer or	IBM_TDB	
		film) ) and photo near (lithograph\$6 and		
ı	Į.	resist)		